



PATENT

UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Cobbley et al.

Serial No.: 10/714,188

Filed: November 14, 2003

For: METHOD FOR PACKAGING FLIP-CHIP SEMICONDUCTOR ASSEMBLIES

Confirmation No.: 9360

Examiner: R. Booth

Group Art Unit: 2812

Attorney Docket No.: 2269-3437.8US
(97-0514.08/US)

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AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Abstract appear on page 9 of this paper.

A **Listing of the Claims** begins on page 10 of this paper.

Amendments to the Drawings appear on page 12 of this paper and include both attached replacement sheets and annotated sheets showing changes.

Remarks begin on page 13 of this paper.

An **Appendix** including amended drawing figures is attached following page 13 of this paper.